



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-02-27
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH1R04A	HNSR*K28L81E	A	ZA41	2017-02-27
Amount		UoM	Unit type	ST ECOPACK Grade
70.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SOJ	4.3 x 2.77 x 2	2	J bend	
Comment	Package: SMA			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	die backside metal	86
Lead	2.63	soft solder	37543

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HNSR*K28L81E					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.940	mg	supplier	die	Silicon (Si)	7440-21-3		0.805	mg	856383	11500
				supplier	metallization	Aluminium (Al)	7429-90-5		0.108	mg	114894	1543
				supplier	Passivation	Silicon Oxide	7631-86-9		0.009	mg	9574	129
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	1064	14
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.006	mg	6383	86
				supplier	polymer die coating	Probimide	proprietary		0.011	mg	11702	157
Leadframe & Clip	Copper and its alloy	26.824	mg	supplier	alloy	Copper (Cu)	7440-50-8		26.811	mg	999515	383014
				supplier	alloy	Zinc (Zn)	7440-66-6		0.001	mg	37	14
				supplier	alloy	Iron (Fe)	7439-89-6		0.003	mg	112	43
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.009	mg	336	129
Soft solder	Solder	2.842	mg	supplier	solder	Silver (Ag)	7440-22-4		0.071	mg	24982	1014
				supplier	solder	Tin (Sn)	7440-31-5		0.143	mg	50317	2043
				JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.628	mg	924701	37543
Encapsulation	Other inorganic materials	38.756	mg	supplier	mold compound	Amorphous Silica	7631-86-9		23.881	mg	616188	341157
				supplier	mold compound	Quartz	14808-60-7		7.751	mg	199995	110729
				supplier	mold compound	epoxy resin	25068-38-6		4.651	mg	120007	66443
				supplier	mold compound	phenolic resin	9003-35-4		2.325	mg	59991	33214
				supplier	mold compound	Bismuth trioxide	1304-76-3		0.027	mg	697	386
				supplier	mold compound	chlorine residue	7782-50-5		0.004	mg	103	57
Connections coating	Solder	0.638	mg	supplier	mold compound	Carbon black	1333-86-4		0.117	mg	3019	1671
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.638	mg	1000000	9114